

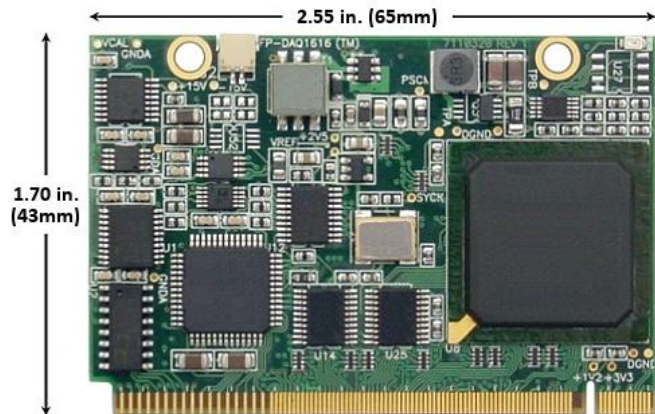
FeaturePak I/O Standard Gains Members, Products, Trade Association

New members include chip-maker VIA Technologies Inc. and board-maker MSC Vertriebs GmbH

April 26, 2010; San Jose, Calif. – (updated April 28, 2010) – The FeaturePak initiative, unveiled last month at Embedded World in Nuremberg, Germany, today announced new members and FeaturePak-related products, and revealed that it is formally organizing as the nonprofit “FeaturePak Trade Association.”

The initiative’s newest members are VIA Technologies Inc., MSC Vertriebs GmbH, and Lippert Embedded Computers GmbH, which join the eight charter members that jointly launched the nascent embedded I/O standard last month.

"FeaturePak I/O modules are well suited to embedded designs based on VIA's low-power, high-performance processors and chipsets," said Alp Sezen, Senior Director of Sales, VIA Embedded Platform Solutions Division, VIA Technologies Inc. "Additionally, FeaturePak sockets are a great way to provide low-profile, small-footprint expansion on carrier boards for COMs such as the Mobile-ITX format VIA EPIA-T700."



About the FeaturePak Standard

The FeaturePak specification defines tiny, application-oriented personality modules – three-fifths the size of a credit card – that snap into low cost, low profile, highly reliable sockets on single board computers (SBCs), computer-on-module (COM) baseboards, and full-custom electronic circuit boards.

FeaturePak modules interface to the host system via a single low-cost, high-density, 230-pin connector, which carries PCI Express, USB, I²C, and several other host-interface signals, plus up to 100 points of application I/O per module. The host interface is CPU agnostic and is compatible with both x86 and RISC architecture systems. Additionally, the modules provide "zero height expansion," in that they fit within the normal component envelope of an SBC or COM baseboard and add no height to PC/104-style I/O expansion stacks.

About the FeaturePak Trade Association

The FeaturePak Trade Association (FPTA), a California Mutual Benefit Corporation, is chartered to maintain, extend, and promote the FeaturePak standard so that all companies in the embedded market can enjoy its benefits. Although anyone can build products based on the FeaturePak specification, FPTA members will gain the ability to:

- Directly influence the evolution of the FeaturePak specification
- Use the FeaturePak logo in association with FeaturePak-related products
- List FeaturePak-related products on FeaturePak.org
- Participate in FPTA marketing and promotional activities

Prior to formation of the FPTA, the FeaturePak specification was maintained by a collaboration among FeaturePak initiative members [Arbor Technology Corp.](#), [Cogent Computer Systems Inc.](#), [congatec AG](#), [Connect Tech Inc.](#), [Douglas Electronics Inc.](#), [Hectronic AB](#), [IXXAT Automation GmbH](#), [Lippert Embedded Computers GmbH](#), [MSC Vertriebs GmbH](#), and [VIA Technologies Inc.](#), plus FeaturePak standard originator [Diamond Systems Corporation](#).

To learn more about the FeaturePak I/O expansion modules standard and the FeaturePak Trade Association, visit [FeaturePak.org](#), or send an email to featurepak@gmail.com. A virtual press kit is available at [FeaturePak.org/press](#).

FeaturePak Initiative Member Media Contacts

Initiative Member	Headquarters	Media Contact	Company Website
Arbor Technology Corp.	Taiwan	Kevin Huang kevinhuang@arbor.com.tw Tel: 886-2-8226-9396	www.arbor.com.tw
Cogent Computer Systems Inc.	USA	Michael Kelly mike@cogcomp.com Tel: +1 401-349-3999	www.cogcomp.com
congatec AG	Germany	North America: Wendy Truax Tel: +1 503-351-0103 Europe: Bettina Lerchenmüller Tel: +49 (0) 8106 24 72 33	www.congatec.com
Connect Tech Inc.	USA	Michele Kasza mkasza@connecttech.com Tel: +1 519-836-1291	www.connecttech.com
Diamond Systems Corp.	USA	Colin McCracken dfastenau@diamondsystems.com Tel: +1 650-810-2500	www.diamondsystems.com
Douglas Electronics Inc.	USA	Chad Pennebaker chad.pennebaker@douglas.com Tel: +1 510-483-8770	www.douglas.com
Hectronic AB	Sweden	Patrik Björklund patrik.bjorklund@hectronic.se Tel: +46 733660704	www.hectronic.se
IXXAT	Germany	Karl Judex judex@ixxat.de Tel: +49-751-56146-133	www.ixxat.de
Lippert Embedded Computers GmbH *	Germany	Markus Friese mfriese@lippertembedded.com	www.lippertembedded.com
MSC Vertriebs GmbH *	Germany	Rosemarie Krause Rosemarie.Krause@gmx.de	www.msc-ge.com
VIA Technologies Inc. *	Taiwan	Joseph Chung JosephChung@viatech.com Tel: +1 510.687.5782	http://www.via.com.tw

FeaturePak-related Products on Display at ESC April 2010

Initiative Member	FeaturePak-related Products
Cogent Computer Systems Inc.	<ul style="list-style-type: none"> • FeaturePak-expandable baseboard for RISC architecture COMs *
Connect Tech Inc.	<ul style="list-style-type: none"> • FeaturePak serial I/O module • PCI Express to FeaturePak adapter
Diamond Systems Corp.	<ul style="list-style-type: none"> • FeaturePak analog I/O module • FeaturePak-expandable baseboard for Intel architecture COMs • FeaturePak digital I/O module * • SUMIT-ISM to FeaturePak adapter *

*** Indicates new members and new products: visit the [FeaturePak Initiative's Virtual Press Kit](#) for further details on all of our members and their FeaturePak-related products.**

FeaturePak™ is a trademark of the FeaturePak Trade Association